

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of ) SEMICONDUCTOR PACKAGE AND  
Kye Chan Park ) FABRICATION METHOD OF THE  
Divisional of ) SAME  
Application No.: 10/167,702 ) Group Art Unit: 2815  
Examiner: Allan R. Wilson  
Filing Date: June 12, 2002 )

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Mail Stop: DIVISIONAL PATENT APPLICATION  
Alexandria, VA 22313-1450

Dear Sir:

Please amend the subject application as follows:

**--CROSS REFERENCE TO RELATED APPLICATION**

This application is a Divisional of U.S. patent application serial No. 10/167,702 entitled "SEMICONDUCTOR PACKAGE AND FABRICATION METHOD OF THE SAME", filed on June 12, 2002 which claims the priority of Korean patent application serial No. 2001-33946, filed June 15, 2001.--

Please delete claims 1-9 which were allowed in the parent application.

Please prosecute claims 10-20 in this application.